



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Moon et al.

Serial No.: 09/874,631

Filed: June 5, 2001

For: FLEXIBLE BALL GRID ARRAY
CHIP SCALE PACKAGES AND
METHODS OF FABRICATION

Examiner: S. Clark

Group Art Unit: 2815

Attorney Docket No.: 4368US (99-0959)

PATENT

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Junker

CERTIFICATE OF MAILING

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Joseph A. Walkowski
Typed/printed name of person whose signature is contained above

AMENDMENT

Box Non Fee Amendment
Commissioner for Patents
Washington, D.C. 20231

Sir:

The following amendments and remarks are filed in response to the Examiner's remarks in the Office Action mailed March 29, 2002, the three-month shortened statutory period for response to which expires on June 29, 2002.

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